



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE  
PATENT APPLICATION

2827

In re the Application of:

**Morrison et al.**

Serial No.: **10/034,827**

Filed: **01/03/2002**

Docket: **TI-31373**

Art Unit: **2827**

Examiner: **J. Mitchell**

**For: CHIP-SCALE PACKAGES STACKED ON FOLDED INTERCONNECTOR FOR  
VERTICAL ASSEMBLY ON SUBSTRATES**

**CHANGE OF CORRESPONDENCE ADDRESS**

Commissioner for Patents  
P. O. Box 1450  
Alexandria, VA 22313-1450

**CERTIFICATE OF MAILING OR TRANSMISSION UNDER 37  
C.F.R. §1.8(a)**

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage for First Class Mail in an envelope addressed to: Commissioner for Patents, Alexandria, VA 22313-1450 or is being facsimile transmitted on:

3-10-04  
Jackie McBride  
Jackie McBride

Sir:

Please change the Correspondence Address for the above-identified patent application to:

**CUSTOMER NUMBER 023494**

Please charge any necessary fees or credit any overpayments to the deposit account of Texas Instruments Incorporated, account number 20-0668.

Texas Instruments Incorporated  
P. O. Box 655474, MS 3999  
Dallas, Texas 75265  
(972) 917-4371

Respectfully submitted,

Wade James Brady III

Wade James Brady III  
Reg. No. 32,080